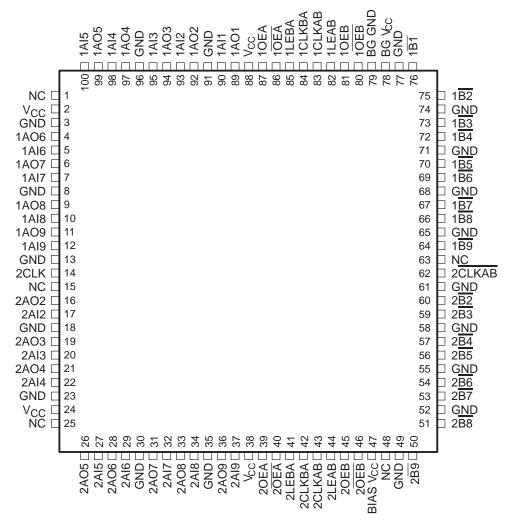
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- Compatible With IEEE Std 1194.1-1991 (BTL)
- TTL A Port, Backplane Transceiver Logic (BTL) B Port
- Open-Collector B-Port Outputs Sink 100 mA
- BIAS V_{CC} Minimizes Signal Distortion During Live Insertion or Withdrawal

- High-Impedance State During Power Up and Power Down
- B-Port Biasing Network Preconditions the Connector and PC Trace to the BTL High-Level Voltage
- TTL-Input Structures Incorporate Active Clamping to Aid in Line Termination

PCA PACKAGE (TOP VIEW)



NC - No internal connection



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SN74FB1651 17-BIT TTL/BTL UNIVERSAL STORAGE TRANSCEIVER WITH BUFFERED CLOCK LINE

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description/ordering information

The SN74FB1651 contains an 8-bit and 9-bit transceiver with a buffered clock. The clock and the transceivers are designed to translate signals between TTL and backplane transceiver-logic (BTL) environments. The device is designed specifically to be compatible with IEEE Std 1194.1-1991.

The \overline{B} port operates at BTL-signal levels. The open-collector \overline{B} ports are specified to sink 100 mA. Two output enables (OEB and \overline{OEB}) are provided for the \overline{B} outputs. When OEB is low, \overline{OEB} is high, or V_{CC} is less than 2.1 V, the \overline{B} port is turned off.

The A port operates at TTL-signal levels. The A outputs reflect the inverse of the data at the \overline{B} port when the A-port output enable (OEA) is high. When OEA is low or when V_{CC} is less than 2.1 V, the A outputs are in the high-impedance state.

BIAS V_{CC} establishes a voltage between 1.62 V and 2.1 V on the BTL outputs when V_{CC} is not connected.

 $\operatorname{BG}\operatorname{V}_{\operatorname{CC}}$ and $\operatorname{BG}\operatorname{GND}$ are the supply inputs for the bias generator.

ORDERING INFORMATION

TA	PACKAG	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
0°C to 70°C	TQFP – PCA	Tube	SN74FB1651PCA	FB1651

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Function Tables

TRANSCEIVER

	INP	UTS		FUNCTION						
OEA	OEA	OEB	OEB	FUNCTION						
Х	Х	Н	L	A data to B bus						
L	Н	Χ	X	B data to A bus						
L	Н	Н	L	A data to B bus, B data to A bus						
Х	Χ	L	Х	D have to detter						
Х	Χ	Χ	Н	B-bus isolation						
Н	Χ	Χ	Х	A-bus isolation						
Х	L	Χ	Χ	A-bus isolation						

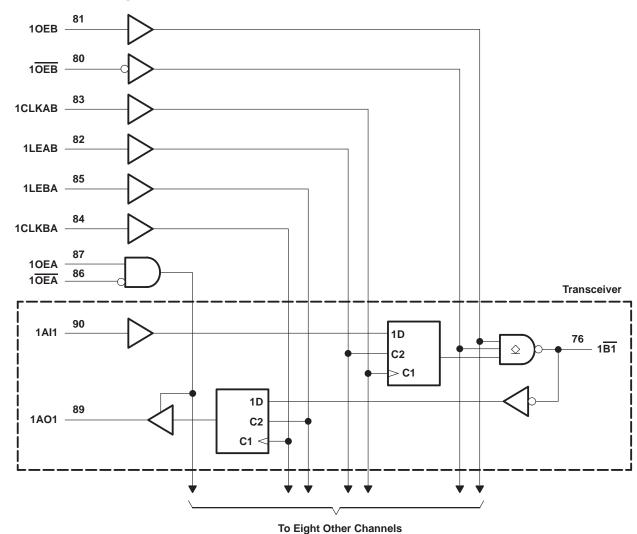
STORAGE MODE

INP	UTS	FUNCTION
LE	CLK	FUNCTION
Н	Х	Transparent
L	\uparrow	Store data
L	L	Storage



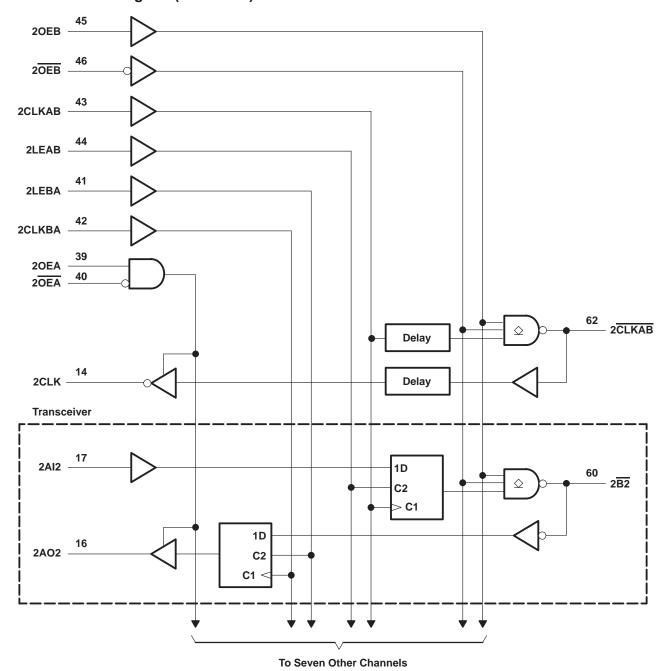
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functional block diagram



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functional block diagram (continued)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} , BIAS V _{CC} , BG V _{CC}	–0.5 V to 7 V
Input voltage range, V _I : Except B port	–1.2 V to 7 V
B port	
Voltage range applied to any \overline{B} output in the disabled or power-off state, V_O	–0.5 V to 3.5 V
Voltage range applied to any output in the high state, V _O	0.5 V to V _{CC}
Input clamp current, I _{IK} : Except B port	
B̄ port	–18 mA
Current applied to any single output in the low state, IO: A port	48 mA
B port	200 mA
Package thermal impedance, θ _{JA} (see Note 1)	22°C/W
Storage temperature range, T _{sta}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

			MIN	NOM	MAX	UNIT
VCC, BG VCC, Supply voltage BIAS VCC					5.5	V
Maria	High level input valte as	B port	1.62		2.3	
VIH	High-level input voltage	Except B port	2			V
Mar	Law laval input valtage	B port	0.75	0.75 1.47		V
V _{IL}	Low-level input voltage	Except B port			0.8	V
ΙΙΚ	Input clamp current				-18	mA
ЮН	High-level output current	A port			-3	mA
	Law bank autout annual	A port			24	4
lor	Low-level output current B port				100	mA
TA	Operating free-air temperature		0		70	°C

NOTE 2: To ensure proper device operation, all unused inputs must be terminated as follows: A and control inputs to V_{CC}(5 V) or GND, and B inputs to GND only. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range

	PARAMETER	TEST CONDITIONS			TYP†	MAX	UNIT
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	B port	V _{CC} = 4.5 V,	I _I = -18 mA			-1.2	V
VIK	Except B port	V _{CC} = 4.5 V,	$I_I = -40 \text{ mA}$			-0.5	V
Vон	AO port	V _{CC} = 4.5 V,	$I_{OH} = -3 \text{ mA}$	2.5	3.3		V
	AO port	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 24 \text{ mA}$		0.35	0.5	
VOL	B port	\/	$I_{OL} = 80 \text{ mA}$	0.75		1.1	V
	B port	V _{CC} = 4.5 V	I _{OL} = 100 mA			1.15	
lį	Except B port	$V_{CC} = 5.5 V,$	V _I = 5.5 V			50	μΑ
I _{IH} ‡	Except B port	V _{CC} = 5.5 V,	V _I = 2.7 V			50	μΑ
. +	Except B port	V _{CC} = 5.5 V,	V _I = 0.5 V			-50	^
111_‡	B port	V _{CC} = 5.5 V,	V _I = 0.75 V			-100	μΑ
lozh	AO port	V _{CC} = 5.5 V,	V _O = 2.7 V			50	μΑ
lozL	AO port	V _{CC} = 5.5 V,	V _O = 0.5 V			-50	μΑ
lozpu	AO port	$V_{CC} = 0 \text{ to } 2.1 \text{ V},$	$V_0 = 0.5 \text{ V to } 2.7 \text{ V}$			50	μΑ
lozpd	AO port	$V_{CC} = 2.1 \text{ V to 0},$	$V_0 = 0.5 \text{ V to } 2.7 \text{ V}$			-50	μΑ
IOH	B port	$V_{CC} = 0 \text{ to } 5.5 \text{ V},$	V _O = 2.1 V			100	μΑ
los§	A port	V _{CC} = 5.5 V,	VO = 0	-30		-150	mA
	A port to B port	.,				100	4
ICC	B port to A port	$V_{CC} = 5.5 \text{ V},$	IO = 0			120	mA
	Al port	V 05V == 05V			5.5		
Ci	Control inputs	V _I = 0.5 V or 2.5 V			5.5		pF
Co	AO ports	V _O = 0.5 V or 2.5 V			5.5		pF
C _{io}	B port per IEEE Std 1194.1-1991	V _{CC} = 0 to 5.5 V				5.5	pF

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

live-insertion specifications over recommended operating free-air temperature range

PAR	AMETER		MIN	MAX	UNIT		
I (DI	AC.\/ \	V _{CC} = 0 to 4.5 V	V 045 0 V	V (DIACV) 45V4655V		450	^
ICC (BI)	AS V _{CC})	V _{CC} = 4.5 V to 5.5 V	$V_B = 0 \text{ to } 2 \text{ V},$	V_I (BIAS V_{CC}) = 4.5 V to 5.5 V		10	μΑ
VO	B port	$V_{CC} = 0$,	V _I (BIAS V _{CC}) = 5 V			2.1	V
		$V_{CC} = 0$,	V _B = 1 V,	V_I (BIAS V_{CC}) = 4.5 V to 5.5 V	-1		
lO	B port	$V_{CC} = 0 \text{ to } 2.2 \text{ V},$	OEB = 0 to 5 V			100	μΑ
		$V_{CC} = 0 \text{ to } 5.5 \text{ V},$	OEB = 0 to 0.8 V			1	mA

[‡] For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current. § Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

					MIN	MAX	UNIT
			MIN	MAX			
fclock	Clock frequency			150		150	MHz
t _W	Pulse duration	CLK or LE	3.3		3.3		ns
	Cotup time	Data before LE	4.8		4.8		20
t _{su}	Setup time	Data before CLK↑	4.9		4.6		ns
4.	Hold time	Data after LE	1.8		1.8		20
^t h	noia time	Data after CLK↑	1.1		1.1		ns

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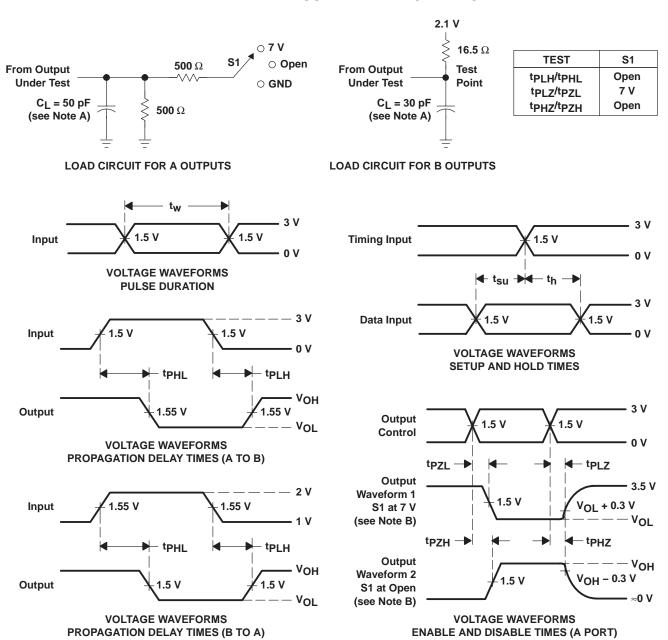
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO	V _C	;C = 5 V \ = 25°C	, ;	MIN	MAX	UNIT
	(INPUT)	(OUTPUT)	MIN	TYP	MAX			
f _{max}			150			150		MHz
t _{PLH}		B	1.8	3.7	5.3	1.8	6.2	
t _{PHL}	Al	В	2.9	4.4	6	2.9	6.6	ns
t _{PLH}	LEAD	B	2.7	4.2	5.8	2.7	6.4	20
^t PHL	LEAB	В	3.5	5	6.5	3.5	7.3	ns
^t PLH	CLKAB	B	2.3	3.9	5.5	2.3	6	20
^t PHL	CLKAD	В	2.9	4.5	6.1	2.9	6.7	ns
^t PLH	2011/40	2 CLKAB	4.6	6.9	8.8	4.6	9.9	
^t PHL	2CLKAB	ZCLKAB	4.9	6.5	8.1	4.9	8.8	ns
t _{PLH}		40	3.5	5.9	7.9	3.5	8	
^t PHL	В	AO	2.2	3.7	5.3	2.2	5.7	ns
t _{PLH}	LEDA	40	1.8	3.2	4.6	1.8	5.1	
^t PHL	LEBA	AO	1.7	3	4.4	1.7	4.7	ns
t _{PLH}	OLIVEA	AO	1.8	3.1	4.6	1.8	5.1	
t _{PHL}	CLKBA		1.7	3.1	4.6	1.7	4.9	ns
t _{PLH}	0011/45	2CLK	6.4	9.7	11.8	6.4	13.4	
^t PHL	2 <mark>CLKAB</mark>		4.1	6.9	8.9	4.1	10.3	ns
t _{PLH}	OFD	B	2.7	4.6	6.4	2.7	6.7	
^t PHL	OEB		2.9	4.1	5.9	2.9	6.6	ns
t _{PLH}		B	2.6	4.3	6.2	2.6	6.6	
^t PHL	OEB		3.4	4.6	6.4	3.4	7	ns
^t PZH	054		1.4	2.9	4.4	1.4	4.9	
t _{PZL}	OEA	AO	1.4	2.6	4	1.4	4.6	ns
^t PHZ	054	40	1.7	3.4	5.1	1.7	5.8	
t _{PLZ}	OEA	AO	2.2	3.6	5	2.2	5.5	ns
^t PZH		40	1.7	3.3	4.7	1.7	5.5	
t _{PZL}	OEA	AO	1.7	3.1	4.4	1.7	5.1	ns
t _{PHZ}	OEA	AO	1.5	2.9	4.5	1.5	5.1	ns
t _{PLZ}	OEA	AO	2	3.1	4.6	2	4.8	115
t _{sk(p)} †	Pulse skew, Al to B or B to	AO OA		1				ns
t _{sk(o)} †	Output skew, AI to B or B to	AO		0.5				ns
t _t	B outputs (1.3 V to 1.8 V)		0.9	1.7		0.5	4.6	no
Transition time	AO outputs (10% to 90%)	0.5	2		0.4	4.2	ns	
B-port input pulse rejection			1			1		ns

[†] Skew values are applicable for through mode only.



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: TTL inputs: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq$ 2.5 ns; BTL inputs: PRR \leq 10 MHz, Z_O = 50 $\Omega,\,t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





PACKAGE OPTION ADDENDUM

10-Aug-2016

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package		•	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing	Q	y (2)	(6)	(3)		(4/5)	
SN74FB1651PCA	ACTIVE	HLQFP	PCA	100	TBD	Call TI	Call TI	0 to 70	FB1651	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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